

STP12NK60Z STF12NK60Z

N-channel 650V @Tjmax- 0.53Ω - 10A - TO-220 /TO-220FP Zener-protected SuperMESH™ Power MOSFET

Features

Туре	V _{DSS} (@Tjmax)	R _{DS(on)}	ID	Pw
STP12NK60Z	650V	<0.640Ω	10A	150W
STF12NK60Z	650V	<0.640Ω	10A	35W

- Extremely high dv/dt capability
- 100% avalanche tested
- Gate charge minimized
- Very low intrinsic capacitances
- Very good manufacturing repeatability

Description

The SuperMESH[™] series is obtained through an extreme optimization of ST's well established strip-based PowerMESH[™] layout. In addition to pushing on-resistance significantly down, specialties is taken to ensure a very good dv/dt capability for the most demanding application. Such series complements ST full range of high voltage Power MOSFETs.

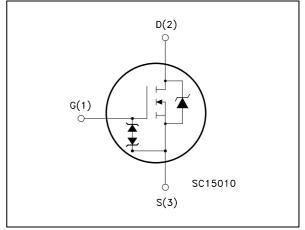
Application

Switching application

Order codes

TO-220FP

Internal schematic diagram



Part number	Marking	Package	Packaging
STP12NK60Z	P12NK60Z	TO-220	Tube
STF12NK60Z	F12NK60Z	TO-220FP	Tube

Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuit	9
4	Package mechanical data 1	0
5	Revision history1	3



1 Electrical ratings

(T_{CASE}=25°C unless otherwise specified)

Table 1.	Absolute maximum ratings
----------	--------------------------

Symbol	Parameter	Value	Unit	
Symbol	Parameter	TO-220	TO-220FP	Unit
V _{DS}	Drain-source voltage (V _{GS} = 0)	600	V	
V _{GS}	Gate-source voltage ±30		V	
Ι _D	Drain current (continuous) at $T_C = 25^{\circ}C$	10	10 ⁽¹⁾	Α
I _D	Drain current (continuous) at $T_C = 100^{\circ}C$ 6.3 6.3 (1)		Α	
I _{DM} ⁽²⁾	Drain current (pulsed)	40	40 ⁽¹⁾	Α
P _{TOT}	Total dissipation at $T_C = 25^{\circ}C$	150	35	W
	Derating factor	1.2	0.27	W/°C
V _{ESD(G-S)}	Gate source ESD(HBM-C=100pF, R=1.5KΩ)		2500	V
dv/dt ⁽³⁾	Peak diode recovery voltage slope	15	V/ns	
V _{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1s;T _C =25°C)		2500	V
Тj	Operating junction temperature -55 to 150		°C	
T _{stg}	Storage temperature	-55 10 1	50	

1. Limited only by maximum temperature allowed

2. Pulse width limited by safe operating area

3. $I_{SD} \leq$ 10A, di/dt \leq 200 A/µs, V_{DD}=480V

Symbol	Parameter	Value	Unit	
Symbol	Falameter	TO-220	TO-220FP	Omt
Rthj-case	Thermal resistance junction-case max	0.83 3.6		°C/W
Rthj-amb	Thermal resistance junction-ambient max	62.5		°C/W
TI	Maximum lead temperature for soldering purpose	300		°C

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by Tj Max)	10	А
E _{AS}	Single pulse avalanche energy (starting Tj=25°C, I _D =I _{AS} , V _{DD} =50V)	260	mJ



2 Electrical characteristics

(T_{CASE}=25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	I _D = 1mA, V _{GS} = 0	600			v
I _{DSS}	Zero gate voltage drain current (V _{GS} = 0)	$V_{DS} = Max rating$ $V_{DS} = Max rating, T_{C}=125^{\circ}C$			1 50	μA μA
I _{GSS}	Gate-body leakage current (V _{DS} = 0)	$V_{GS} = \pm 20V$			±10	μA
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100 \mu A$	3	3.75	4.5	V
R _{DS(on)}	Static drain-source on resistance	V _{GS} = 10V, I _D = 5A		0.53	0.64	Ω

Table 4. On/off

Table 5. Dynamic

	,					
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
g _{fs} ⁽¹⁾	Forward transconductance	V _{DS} =10V _, I _D =5A		9		S
C _{iss} C _{oss} C _{rss}	Input capacitance Output capacitance Reverse transfer capacitance	V _{DS} = 25V, f = 1MHz, V _{GS} = 0		1740 195 49		pF pF pF
C _{oss eq.} ⁽²⁾	Equivalent output capacitance	V_{GS} = 0V, V_{DS} = 0V to 480V		101		pF
Td _(on) T _r Td _(off) t _f	Turn-on delay time Rise time Turn-off delay time Fall time	$V_{DD} = 300V, I_D = 5A, R_G = 4.7\Omega$ $V_{GS} = 10V,$ (see Figure 16)		22.5 18.5 55 31.5		ns ns ns ns
Q _g Q _{gs} Q _{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 480V, I_D = 10A,$ $V_{GS} = 10V$ (see Figure 17)		59 10 32		nC nC nC

1. Pulsed: pulse duration = $300 \ \mu$ s, duty cycle 1.5%

2. $C_{oss~eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS}



Symbol	Parameter	Test conditions	Min	Тур.	Max	Unit
I _{SD} I _{SDM} ⁽¹⁾	Source-drain current Source-drain current (pulsed)				10 40	A A
V _{SD} ⁽²⁾	Forward on voltage	I _{SD} = 10A, V _{GS} = 0			1.6	V
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 10A, di/dt = 100A/\mu s$ $V_{DD} = 50V, T_j = 25^{\circ}C$ <i>(see Figure 21)</i>		358 3 17		ns μC Α
t _{rr} Q _{rr} I _{RRM}	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 10A, di/dt = 100A/\mu s$ $V_{DD} = 50V, T_j = 150^{\circ}C$ (see Figure 21)		460 4.2 18.2		ns μC Α

 Table 6.
 Source drain diode

1. Pulse width limited by safe operating area

2. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5%

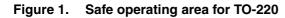
Table 7. Gate-source Zener diode

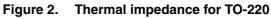
Symbol	Parameter	Test conditions	Min	Тур	Max	Unit
BV _{GSO} ⁽¹⁾	Gate-Source breakdown voltage	Igs=± 1mA (Open drain)	30			V

 The built-in back-to-back Zener diodes have specifically been designed to enhance not only the device's ESD capability, but also to make them safely absorb possible voltage transients that may occasionally be applied from gate to source. In this respect the Zener voltage is appropriate to achieve an efficient and cost-effective intervention to protect the device's integrity. These integrated Zener diodes thus avoid the usage of external components.



2.1 Electrical characteristics (curves)





Thermal impedance for TO-220FP

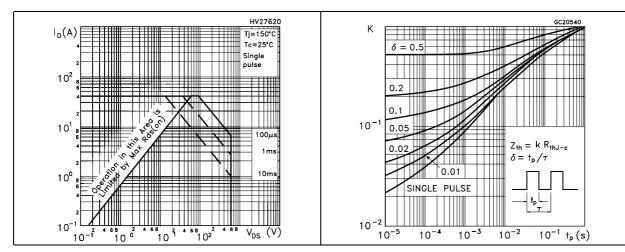


Figure 3. Safe operating area for TO-220FP

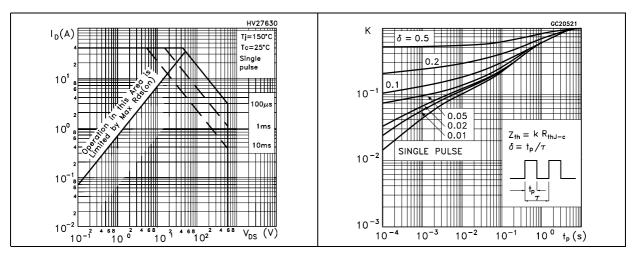
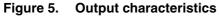


Figure 4.





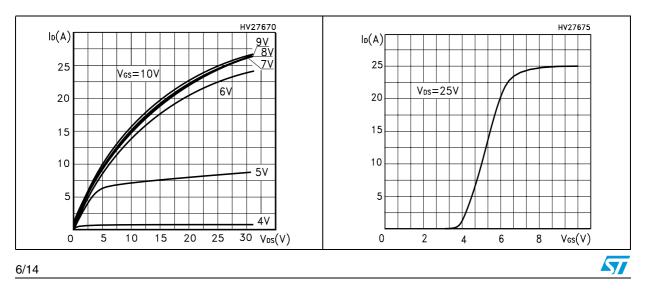


Figure 7. Transconductance



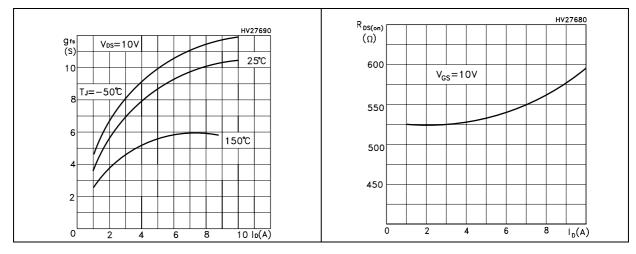


Figure 9. Gate charge vs gate-source voltage Figure 10. Capacitance variations

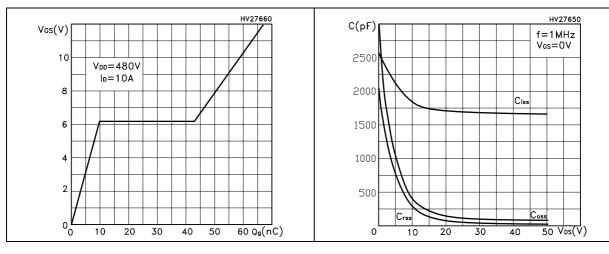
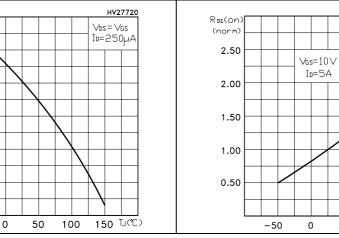
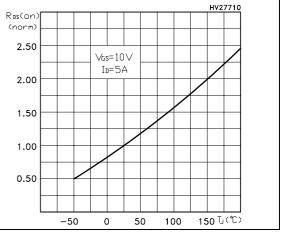


Figure 11. Normalized gate threshold voltage vs temperature

Figure 12. Normalized on resistance vs temperature





57

Vas(th)

(norm)

1.1

1.0

0.9

0.8

0.7

0.6

-50

700 L

2



6

8

10 ISD(A)

Figure 15. Maximum avalanche energy vs temperature

4

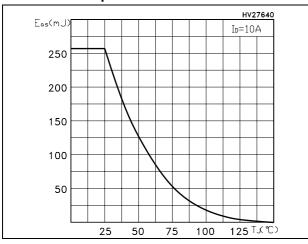
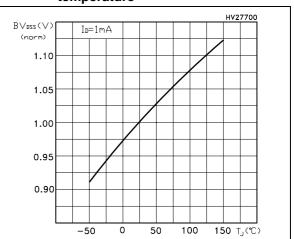


Figure 14. Normalized breakdown voltage vs temperature



57

3 Test circuit

Figure 16. Switching times test circuit for resistive load

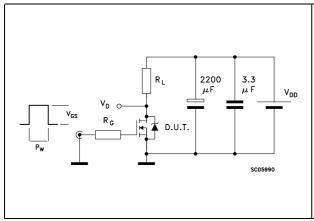
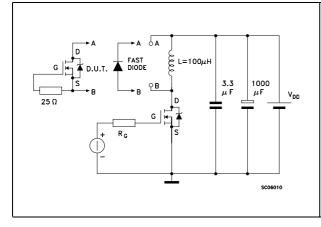
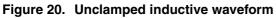


Figure 18. Test circuit for inductive load switching and diode recovery times





57

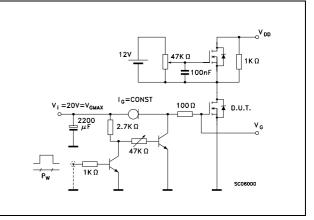


Figure 19. Unclamped inductive load test circuit

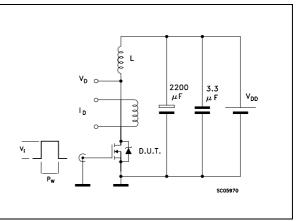


Figure 21. Switching time waveform

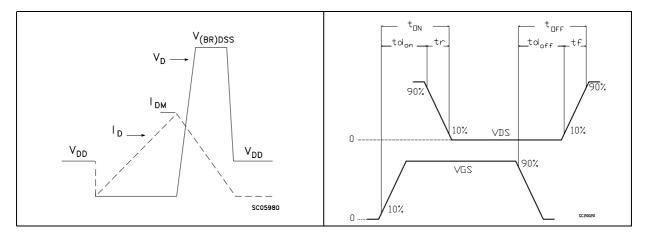


Figure 17. Gate charge test circuit

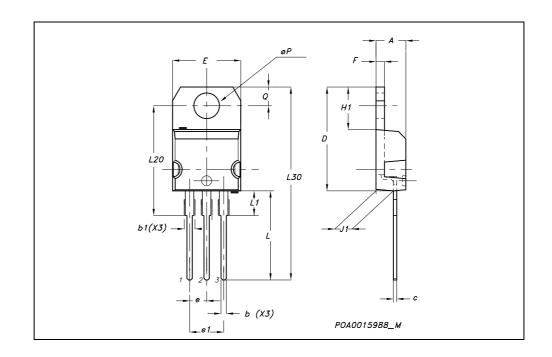
4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: *www.st.com*



DIM.	mm.			inch		
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
С	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
Е	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116

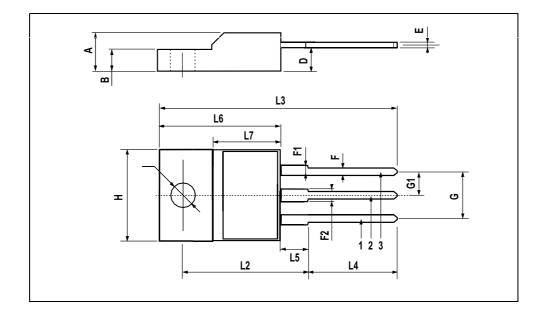
TO-220 MECHANICAL DATA



57

DIM.	mm.			inch		
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126





5 Revision history

Table 8. Revision history

Date	Revision	Changes
12-Apr-2004	1	First release
06-Sep-2005	2	Inserted ecopack indication
13-Sep-2005	3	Final version
05-Sep-2006	4	The document has been reformatted
26-Apr-2007	5	The document has been updated on 1: Electrical ratings



Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2007 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan -Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

